ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

15-Apr-2009

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16248

TITLE: Qualification of OSPI for Assembly and Final Test for SO8 Packages

PROPOSED FIRST SHIP DATE: 14-Jul-2009

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly Site

AFFECTED PRODUCT DIVISION(S): Standard Products Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Angela Tam <Angela.Tam@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Richard Clemente at ffwtmt@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the Final PCN to Initial PCN 16173 located at www.onsemi.com announcing the successful completion of the qualification for the ON Semiconductor internal manufacturing site in Carmona, Philippines (OSPI) as an additional manufacturing site for SO-8 package assembly and final test.

There will be no changes in the wafer/die source. Device functionality will be unchanged. Device parameters will continue to meet all Data Book specifications and reliability will continue to meet or exceed ON Semiconductor standards.

This change is classified as capacity expansion. The products listed below can be manufactured at either OSPI or the existing facility, Unisem in Indonesia, once the final PCN expires.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:
Reliability testing was performed on 1 lot each of qualification vehicles NUD4001DR2G, NIS5112D1R2G, and SIS5143D2R2G.

Test	Conditions	Duration	Results (Rejects/Sample Size)
HTOL	T_J = 150 ºC	1008 hours	Pass (0/80 per lot * 3 lots)
PC + Temp Cycle	-65ºC/150ºC	1000 cycles	Pass (0/80 per lot * 3 lots)
PC + HAST	130ºC/85RH	96 hours	Pass (0/80 per lot * 3 lots)
PC + AC	121ºC/15PSIG	96 hours	Pass (0/80 per lot * 3 lots)
Solderability			Pass (0/15 per lot * 3 lots)

ELECTRICAL CHARACTERISTIC SUMMARY:
Final test correlation between OSPI test and Unisem test was performed on the affected devices. All production test parameters were evaluated and passed final test correlation.

CHANGED PART IDENTIFICATION:
Devices marked with date code 0928 (2009 WW28) or later may be assembled and final tested at either of the qualified sites (On Semiconductor in Carmona, Philippine or Unisem in Indonesia).

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AFFECTED DEVICE LIST

NUD4001DR2
NUD4001DR2G
NUD4011DR2
NUD4011DR2G
NIS5112D1R2G
NIS5112D2R2G
SIS5142D2R2G